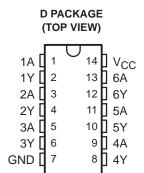
- Controlled Baseline
  - One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- 2-V to 6-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 6 V
- Max t<sub>pd</sub> of 7 ns at 5 V



#### description/ordering information

The SN74AC04 contains six independent inverters. The device performs the Boolean function  $Y = \overline{A}$ .

#### ORDERING INFORMATION

TA	PACKAGE	<b>‡</b>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOIC - D	Tape and reel	SN74AC04MDREP	SAC04MEP

<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

### FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram, each inverter (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	$-0.5$ V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Output voltage range, V <sub>O</sub> (see Note 1)	$-0.5 \text{ V}$ to $\text{V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±200 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	86°C/W
Storage temperature range, T <sub>stq</sub> (see Note 3)	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 3. Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep\_quality for additional information on enhanced plastic packaging.

#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage	2	6	V	
		V <sub>CC</sub> = 3 V	2.1		
٧ <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15		V
	VIH High-level input voltage  VIL Low-level input voltage  VI Input voltage  VO Output voltage  IOH High-level output current	V <sub>CC</sub> = 5.5 V	3.85		
		V <sub>CC</sub> = 3 V		0.9	
$V_{IL}$	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$		1.35	V
		$V_{CC} = 5.5 \text{ V}$		1.65	
٧ <sub>I</sub>	Input voltage		0	VCC	V
VO	Output voltage		0	VCC	V
		V <sub>CC</sub> = 3 V		-12	
lOH	High-level output current	$V_{CC} = 4.5 \text{ V}$		-24	mA
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	$V_{CC} = 5.5 \text{ V}$		-24		
		V <sub>CC</sub> = 3 V		12	
lOL	Low-level output current	V <sub>CC</sub> = 4.5 V		24	mA
$I_{OH}$ High-level output current $I_{OL}$ Low-level output current $\Delta t/\Delta v$ Input transition rise or fall rate	V <sub>CC</sub> = 5.5 V		24		
Δt/Δν	Input transition rise or fall rate			8	ns/V
TA	Operating free-air temperature		-55	125	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEGT CONDITIONS	١,,	Т	A = 25°C	;	MINI	BA A V	LINUT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
		3 V	2.9	2.99		2.9		
	I <sub>OH</sub> = -50 μA	4.5 V	4.4	4.49		4.4		
V		5.5 V	5.4	5.49		5.4		V
VOH	I <sub>OH</sub> = −12 mA	3 V	2.56			2.4		V
	044	4.5 V	3.86			3.7		
	I <sub>OH</sub> = -24 mA	5.5 V	4.86			4.7		
		3 V		0.002	0.1		0.1	
	I <sub>OL</sub> = 50 μA	4.5 V		0.001	0.1		0.1	
.,		5.5 V		0.001	0.1		0.1	
VOL	I <sub>OL</sub> = 12 mA	3 V			0.36		0.5	V
	044	4.5 V			0.36		0.5	
	I <sub>OL</sub> = 24 mA	5.5 V			0.36		0.5	
I <sub>I</sub>	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40	μΑ
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND			2.8				pF

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	FROM TO						
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	^	V	1.5	4.5	9	1	11	no
t <sub>PHL</sub>	A	T	1.5	4.5	8.5	1	10	ns

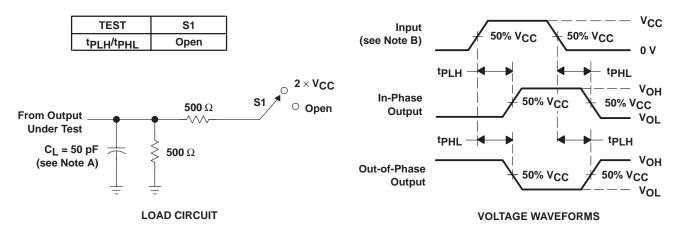
## switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	T,	չ = 25°C	;	MIN	MAX	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX			UNIT
<sup>t</sup> PLH	^	V	1.5	4	7	1	8.5	no
tPHL	A	Ĭ	1.5	3.5	6.5	1	7.5	ns

### operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CON	NDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	$C_L = 50 pF$ ,	f = 1 MHz	45	pF

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2.5$  ns.  $t_f \leq 2.5$  ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







ti.com 18-Sep-2008

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AC04MDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04614-01XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN74AC04-EP:

Catalog: SN74AC04

Automotive: SN74AC04-Q1

• Military: SN54AC04

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications



#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

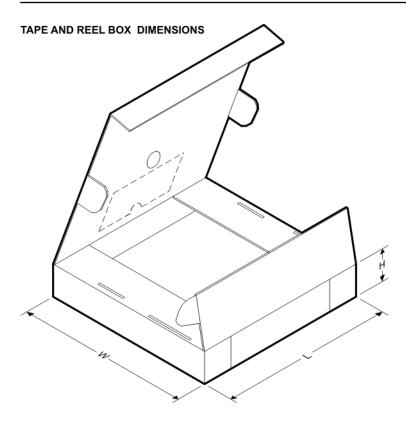
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC04MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1





#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC04MDREP	SOIC	D	14	2500	333.2	345.9	28.6

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